



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-11-11
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	IPD MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7BVT*066SBL1	A	SH1A	2015-11-11
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10,15.5,4.5	3	Through-hole	
Comment	Package: TO 220 I CLIP, MD valid for CP:BTA06-600CWRG			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-15th June 2015			
Query			Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH			true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application
			ppm in product

Material Composition Declaration						Mfr Item Name	7BVT*066SBL1	1900				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die (s)	Other inorganic materials	5.695	mg	supplier	die	Silicon (Si)	7440-21-3		5.022	mg	881826	2643
Die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.046	mg	8077	24
Die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.064	mg	11238	34
Die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.014	mg	2458	7
Die (s)				supplier	passivation	Alumina	1344-28-1		0.041	mg	7199	22
Die (s)				supplier	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and	0.365	mg	64091	192
Die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1054	3
Die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.137	mg	24056	72
Leadframe	Copper & its alloys	1604.661	mg	supplier	alloy	Copper (Cu)	7440-50-8		1599.275	mg	996644	841724
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.737	mg	459	388
Leadframe				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		1.345	mg	838	708
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		3.304	mg	2059	1739
Soft solder		4.165	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.853	mg	925090	2028
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.208	mg	49940	109
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.104	mg	24970	55
Bonding wire	Other inorganic materials	31.625		supplier	Slug + Trigger	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645
Encapsulation	Other Organic Materials	158.264	mg	supplier	mold compound	Silica, vitreous	60676-86-0		120.281	mg	760002	63306
Encapsulation				supplier	mold compound	Phenol resin	9003-35-4		9.496	mg	60001	4998
Encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.266	mg	7999	666
Encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		16.143	mg	102000	8496
Encapsulation				supplier	mold compound	Metal hydroxide	21645-51-2		3.165	mg	19998	1666
Encapsulation				supplier	mold compound	Others	Proprietary		7.913	mg	49999	4165
Solder paste	Solder	0.076	mg	supplier	solder	Lead (Pb)	7439-92-1		0.064	mg	842105	34
Solder paste				supplier		Antimony (Sb)	7440-36-0		0.008	mg	105263	4
Solder paste				supplier		Tin (Sn)	7440-31-5		0.004	mg	52632	2
Connections coating	Other inorganic materials	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323
Subelement	Ceramics / Glass	89.2	mg	supplier	Ceramic isolator	Nickel (Ni)	7440-02-0		1.07	mg	11996	563
Subelement				supplier	Ceramic isolator	Phosphorus (P)	7723-14-0		0.08	mg	897	42
subelement				supplier	Ceramic isolator	Manganese (Mn)	7439-96-5		3.479	mg	39002	1831
subelement				supplier	Ceramic isolator	Titanium (Ti)	7440-32-6		0.366	mg	4103	193
subelement				supplier	Ceramic isolator	Molybdenum oxide	1313-27-5		4.46	mg	50000	2347
subelement				supplier	Ceramic isolator	Alumina (Al2O3)	1344-28-1		79.745	mg	894002	41971